

Title (en)  
METHOD FOR MAKING A MICROCIRCUIT CARD

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINER MIKROSCHALTUNGSKARTE

Title (fr)  
PROCEDE DE REALISATION D UNE CARTE A MICROCIRCUIT

Publication  
**EP 1464083 A2 20041006 (FR)**

Application  
**EP 02804942 A 20021218**

Priority  
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Abstract (en)  
[origin: WO03052822A2] invention concerns a method for mounting a microcircuit module in a card body to make the card non-detachable without damage. The method consists in fixing the module (22) in a cavity (12) of the card body (11) with a resin after adjusting the adherence of the resin (30) on the wall of the cavity (12) so that it is markedly higher than its adherence on the module (22).

IPC 1-7  
**H01L 23/498**

IPC 8 full level  
**B42D 25/305** (2014.01); **B42D 25/435** (2014.01); **B42D 25/455** (2014.01); **B42D 25/47** (2014.01); **G06K 19/073** (2006.01); **G06K 19/077** (2006.01); **G06K 19/10** (2006.01); **H01L 23/498** (2006.01); **H05K 1/18** (2006.01); **H05K 3/00** (2006.01); **H05K 3/30** (2006.01)

CPC (source: EP US)  
**G06K 19/073** (2013.01 - EP US); **G06K 19/07372** (2013.01 - EP US); **G06K 19/07745** (2013.01 - EP US); **G06K 19/07747** (2013.01 - EP US); **H01L 23/49855** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48228** (2013.01 - EP US); **H01L 2924/1815** (2013.01 - EP US); **H05K 1/183** (2013.01 - EP US); **H05K 3/0044** (2013.01 - EP US); **H05K 3/305** (2013.01 - EP US); **Y10T 29/49117** (2015.01 - EP US); **Y10T 29/49126** (2015.01 - EP US); **Y10T 29/4913** (2015.01 - EP US); **Y10T 29/49146** (2015.01 - EP US)

C-Set (source: EP US)  
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See references of WO 03052822A2

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